KYOTO ELECTRONICS MANUFACTURING CO., LTD.

Application Memo Copper Sulfate in Plating Solution

Industry Instrument Measurement method Standards

Nonferrous metal Automatic potentiometric titrator Redox titration

1. Overview

Copper sulfate in copper sulfate plating solution is measured by titration with 0.025mol/L sodium thiosulfate after the sample is added with pure water, ammonia water and 30% scetic acid and 20% potassium iodide.

The endpoint is the maximum inflexion on the titration curve. The copper sulfate concentration is calculated from the titration volume of sodium thiosulfate.

2. Apparatus

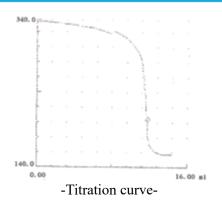
Main unit Automatic potentiometric titrator (preamplifier STD)

Electrode Platinum electrode Ceramic reference electrode

3. Reagents

Titrant	0.025mo1/L sodium thiosulfate (f=1.004)
Solvent	Pure water
Additive	Ammonia water, 30% acetic acid, 20% potassium iodide

4. Example



-Measurement results-				
	Sample	Titration	Copper sulfate	
	(mL)	(mL)	(g/L)	
1	5.0	11.7575	9.420	

Please feel free to contact us for any further information. <Contact>Kyoto Electronics Manufacturing Co., Ltd. Overseas Sales & Marketing Sect.

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